

REMARKS

The foregoing amendment and the following arguments are provided to impart precision to the claims, by more particularly pointing out the invention, rather than to avoid prior art.

35 U.S.C. § 102(e) Rejections

Examiner rejected claims 1-3 and 5-18 as being anticipated by Li et al., U.S. Patent No. 6,148,906.

Examiner rejected claim 4 as being anticipated by Mecredy, III et al., U.S. Patent No. 6,118,655.

Examiner rejected claims 19-23 as being anticipated by Li et al.

Examiner rejected claims 24-28 as being anticipated by Maruyama et al., U.S. Patent No. 6,069,793.

"To anticipate a claims, the reference must teach every element of the claim. A claim is anticipated only if each and every element as set forth in the claim is found, either expressly or inherently described, in a single prior art reference." (Manual of Patent Examining Procedures (MPEP) ¶ 2131.)

Independent claims 1 and 19 of the present application includes limitations not disclosed or taught by Li et al. As a result, claims 1 and 19 are not anticipated by Li et al. Furthermore, independent claim 24 includes limitations not disclosed or taught by Maruyama et al. There claim 19 is not anticipated by Li et al.

In particular, independent claims 1, 19, and 24 include the limitation of a *thermo-siphon device formed as an integral part of a wall of the chassis*. Neither Li et al. nor Maruyama et al. disclose or suggest a *thermo-siphon device formed as an integral part of a wall of the chassis*, as is claimed by applicant.

Rather, Li et al., simply discloses a:

Heat pipe is installed within the case of a notebook or laptop computer of the type havin a cover attached via a hing to the case wherein a video display mounted a front surface of the cover may be viewed when the cover is open. An end of a flat_plate heat sink, either mounted on, mating with, or forming an integral part of the back cover, thermally contacts the heat pipe when the cover is open. (Li et al., col. 2, lines 57-65, also see Figure 8 of Li et al.)

Maruyama et al., only discloses:

The CPU module further provides a heat release plate **one side of which is pasted with the printed circuit board** and the other side which is substantially planar. The printed board has a cavity formed therein so that the processor may be fitted in the cavity in a bare-chip state. (Maruyama et al. abstract)

Therefore, as a result of Li et al. and Maruyama et al., failing to disclose or suggest the limitation of a *thermo-siphon device formed as an integral part of a wall of the chassis*, as is claimed by applicant, applicant's independent claims 1, 19, and 24 are not anticipated by Li et al. or Maruyama et al.

Furthermore, the remaining claims depend from one of independent claims 1, 19, and 24, and therefore include the distinguishing claim limitations of claims 1, 19, and 24, as discussed above. As a result, the remaining claims are

also not anticipated by Li et al. or Maruyama et al., and are also patentable over Li et al. or Maruyama et al.

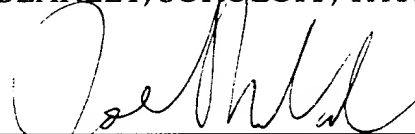
CONCLUSION

Applicant respectfully submits the present application is in condition for allowance. If the Examiner believes a telephone conference would expedite or assist in the allowance of the present application, the Examiner is invited to call John Ward at (408) 720-8300, x237.

Authorization is hereby given to charge our Deposit Account No. 02-2666 for any charges that may be due.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN



Date: July 8, 2002

John P. Ward
Reg. No. 40,216

12400 Wilshire Boulevard
Seventh Floor
Los Angeles, CA 90025-1026
(408) 720-8300

ATTACHMENT A

A marked-up version of the amended claims is as follows:

1. (Amended) A device enclosure comprising:

a chassis; and

a thermo-siphon device formed as an integral part of a wall of the chassis
[embedded in an enclosure skin].

2. The device of claim 1, wherein the device is an electronic device.

3. The device of claim 2, wherein the device enclosure is a computer chassis.

4. The device of claim 1, wherein the device is a non-electronic device.

5. The device of claim 1, wherein the thermo-siphon device is a heat pipe.

6. The device of claim 1, wherein the thermo-siphon device is a strip of a high efficiency conduit material.

7. Canceled. ✓

8. Canceled. ✓

9. (Amended) The device of claim 1, wherein the [skin] wall is fabricated from a metallic material.

10.(Amended) The device of claim 1, wherein the thermo-siphon device is embedded in a [skin] cavity of the wall.

11. (Amended) The device of claim 10, wherein the cavity is created during a fabrication process of the [skin] wall.

12. (Amended) The device of claim 1, wherein the [skin] wall partially encloses the thermo-siphon device.

13. The device of claim 12, wherein a portion of the thermo-siphon device is exposed to an interior of the enclosure.

14. The device of claim 12, wherein a portion of the thermo-siphon device is exposed to a heat sink.

15. (Canceled)

16. (Canceled)

17. (Amended) The device of claim 1, wherein the thermo-siphon device is secured to a [skin] wall cavity through the means selected from the group consisting of a support provided by [skin] cavity walls, a thermal epoxy, and an interference fit with the skin cavity.

18. The device of claim 1, wherein a metallic plate interfaces a heat source with the thermo-siphon device.

19. (Amended) A system comprising:

a chassis; and

a thermo-siphon device formed as an integral part of a wall of the chassis

[a housing including a thermo-siphon device embedded in a housing skin].

20. The system of claim 19, wherein the thermo-siphon device is a heat pipe.

21. The system of claim 19, wherein the thermo-siphon device is a strip of high efficiency conduit material.

22. The system of claim 19, wherein the housing is a computer chassis.

23. Canceled ✓

24. (Amended) A computer chassis comprising:

a chassis; and

a thermo-siphon device formed as an integral part of a wall of the chassis

[a thermo-siphon device embedded in a computer chassis skin].

25. The computer chassis of claim 24, wherein the thermo-siphon device is a heat pipe.

26. The computer chassis of claim 24, wherein the computer chassis is a notebook computer base.

27. Canceled ✓

28. (Amended) The computer chassis of claim 27, wherein the thermo-siphon device is embedded in the wall [skin] during the manufacturing process of the skin.